

(12) **United States Design Patent** (10) **Patent No.:** **US D802,790 S**
Tauchi et al. (45) **Date of Patent:** **** Nov. 14, 2017**

(54) **COVER RING FOR A PLASMA PROCESSING APPARATUS**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **24-01**

(52) **U.S. Cl.**
 USPC **D24/232; D13/182**

(58) **Field of Classification Search**
 USPC D24/169, 186, 216, 231, 232; D13/122, D13/138, 144, 182, 199, 158-177; D15/144, 144.1, 199, 138, 133
 CPC ... C23C 16/42; C23C 16/4412; C23C 16/455; C23C 16/00; C23C 16/4585; C30B 25/12; C30B 25/14; C23F 1/00; H01J 37/32623; H01J 37/32633; H01J 37/32642; H01J 37/32651; H01L 21/67069
 See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a cover ring for a plasma processing apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a cover ring for a plasma processing apparatus showing my new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

FIG. 4 is a left side elevational view thereof;

FIG. 5 is a right side elevational view thereof;

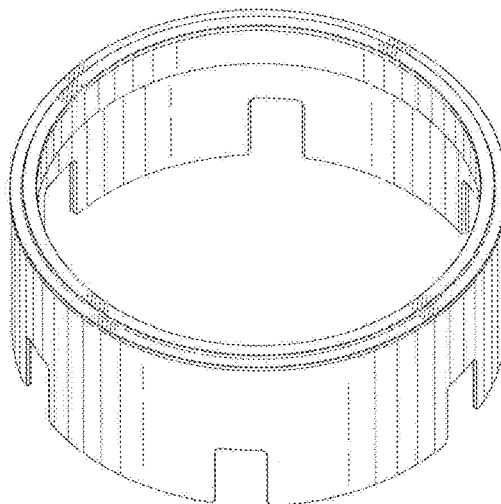
FIG. 6 is a top plan view thereof;

FIG. 7 is a bottom plan view thereof;

FIG. 8 is a cross-sectional view taken along line 8-8 of FIG. 6; and,

FIG. 9 is an enlarged portion view taken along line 9-9 of FIG. 8.

1 Claim, 7 Drawing Sheets



(56)

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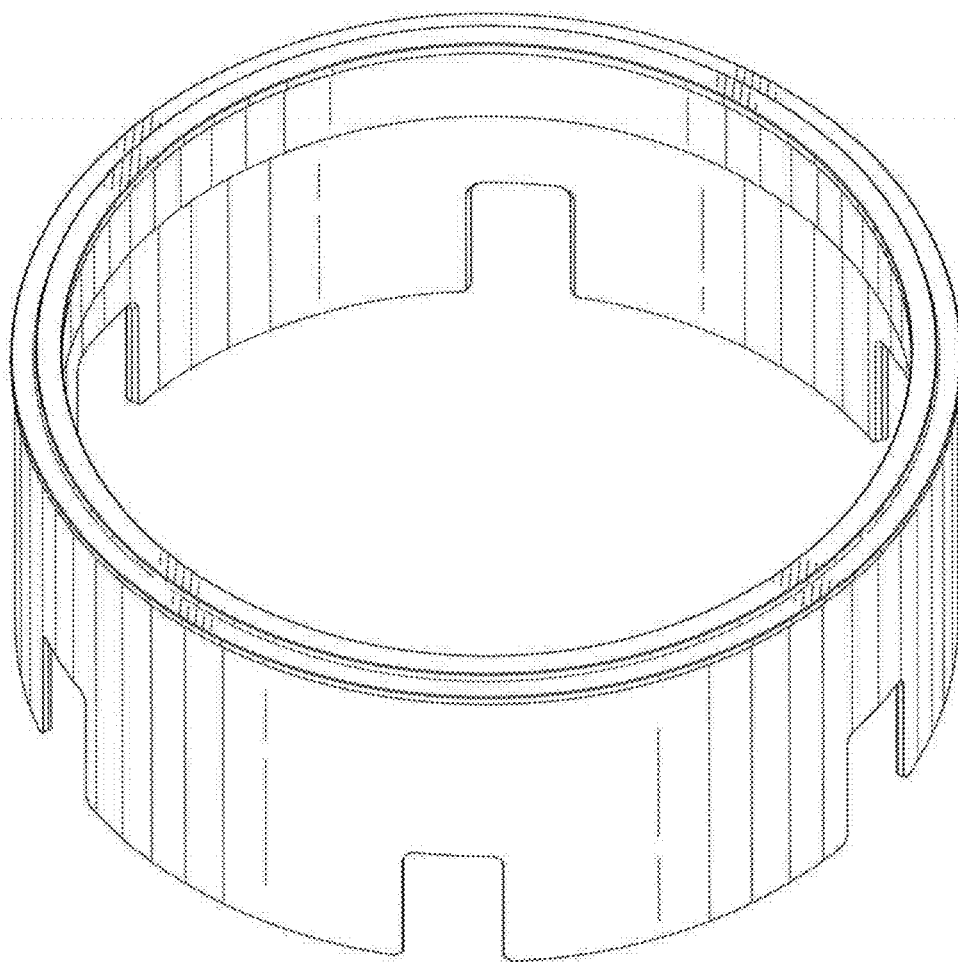


FIG. 1

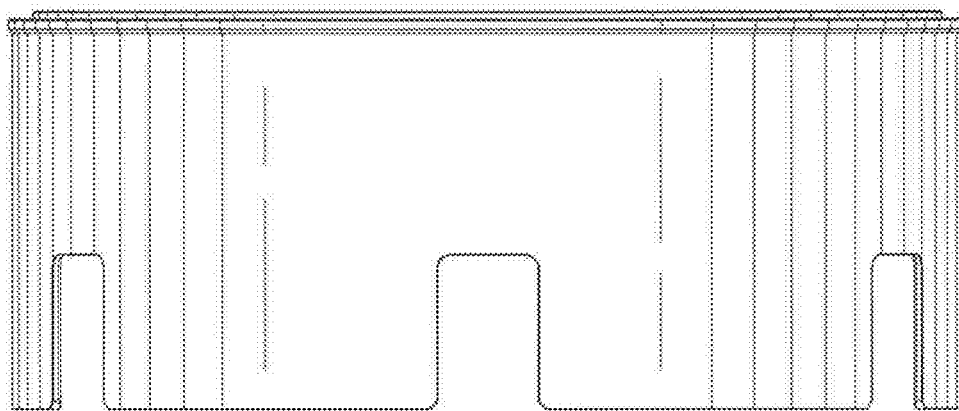


FIG. 2

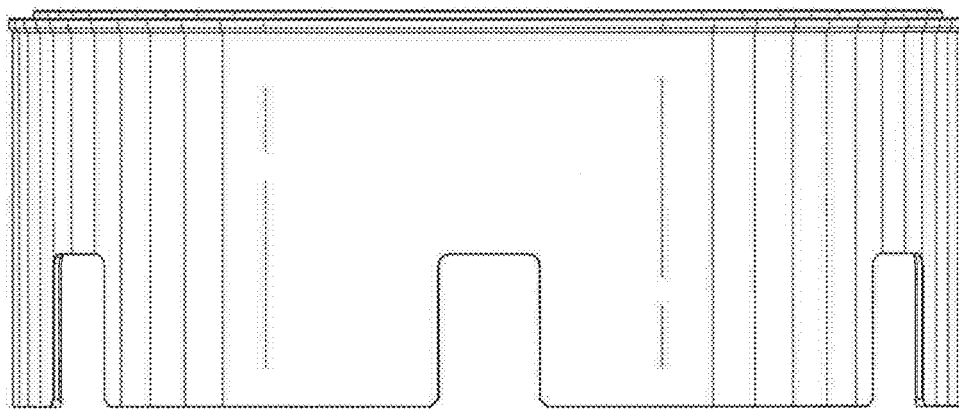


FIG. 3

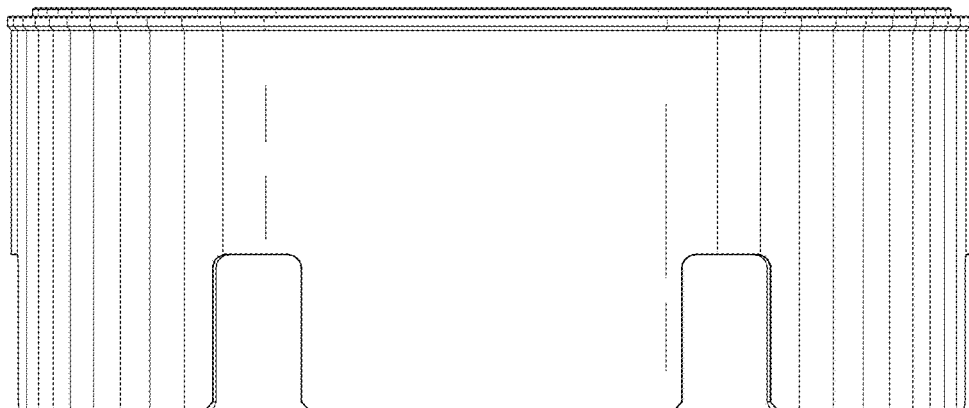


FIG. 4

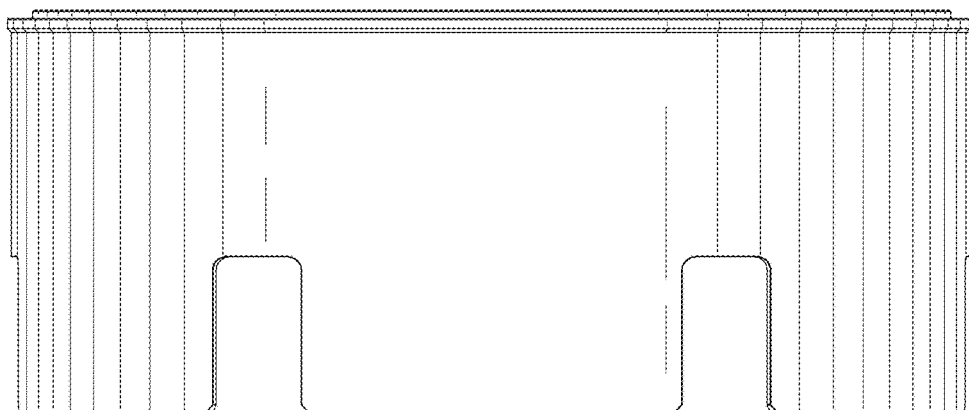


FIG. 5

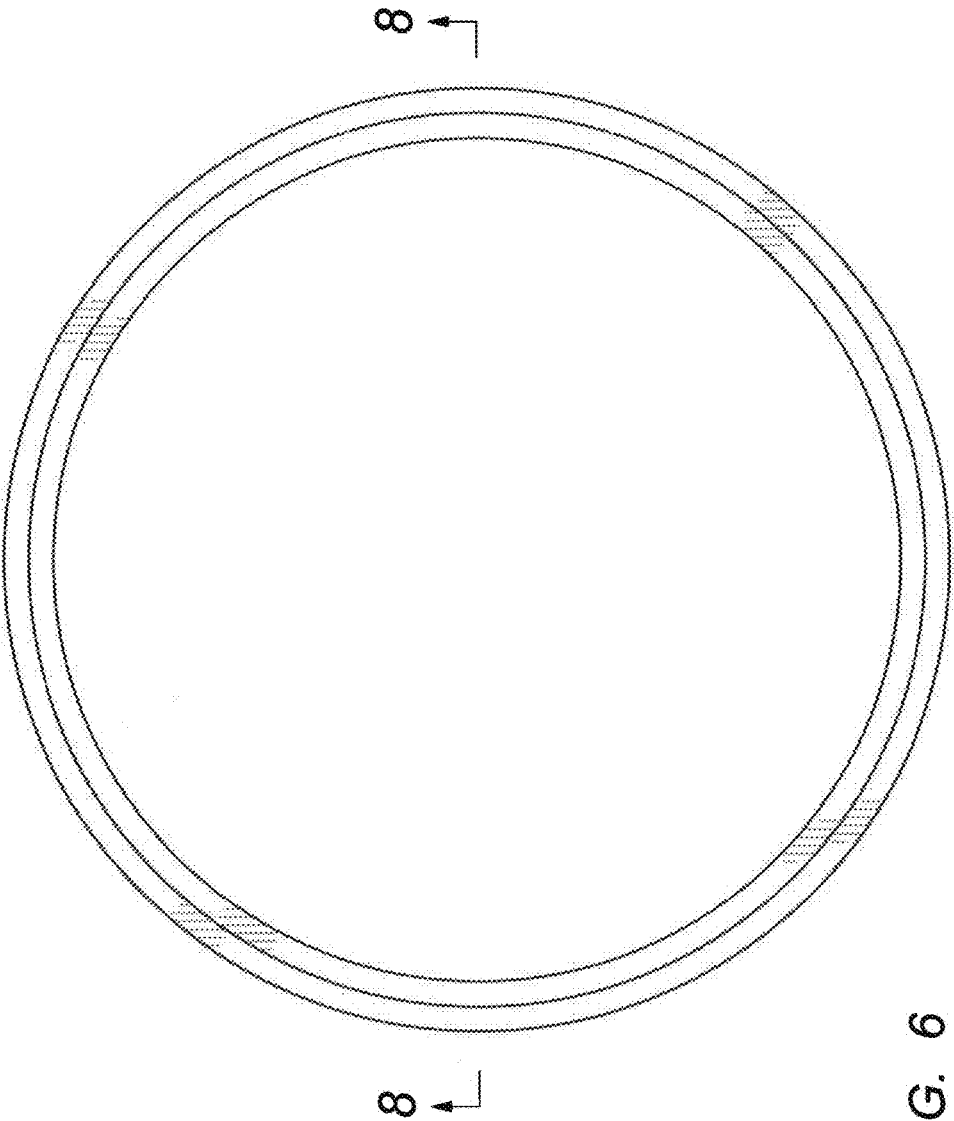


FIG. 6

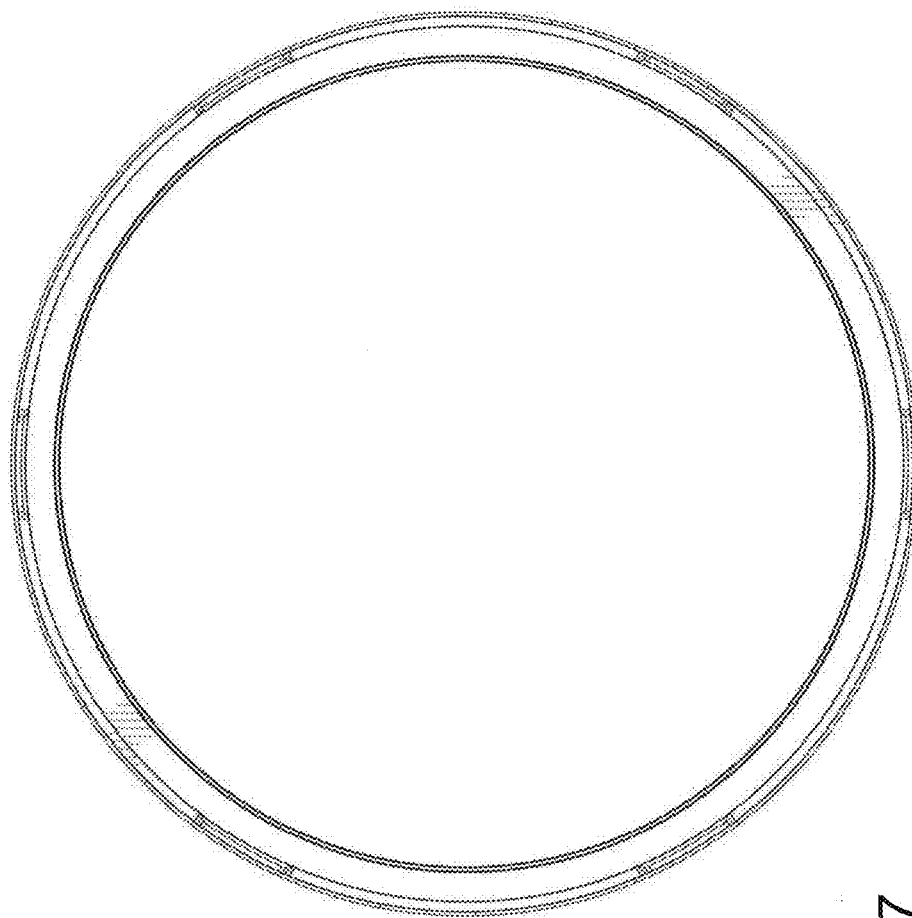


FIG. 7

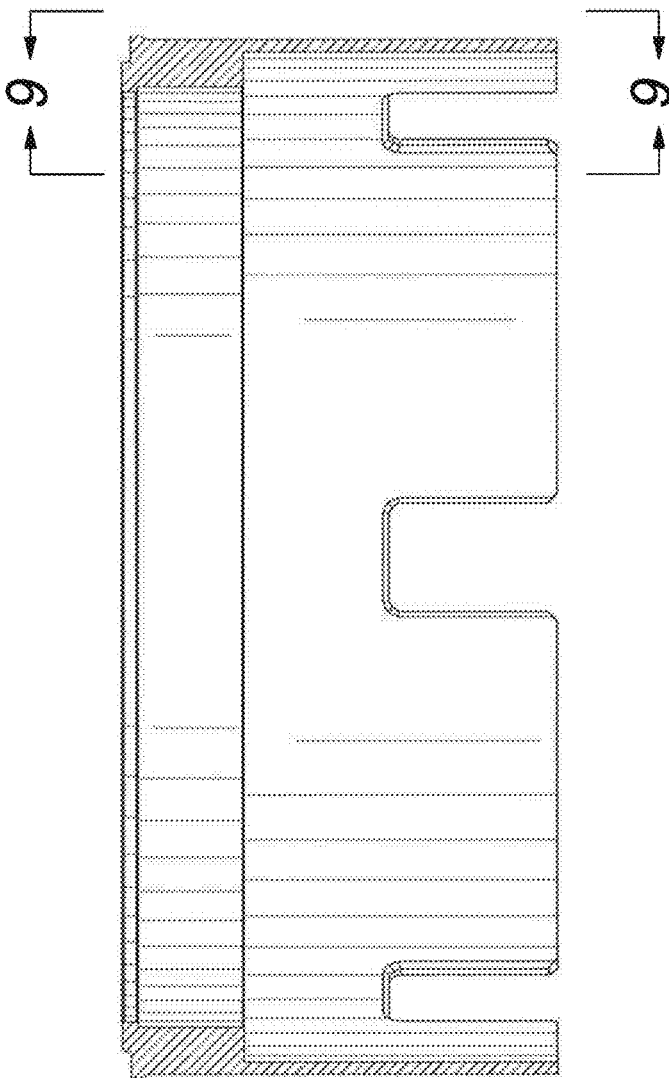


FIG. 8

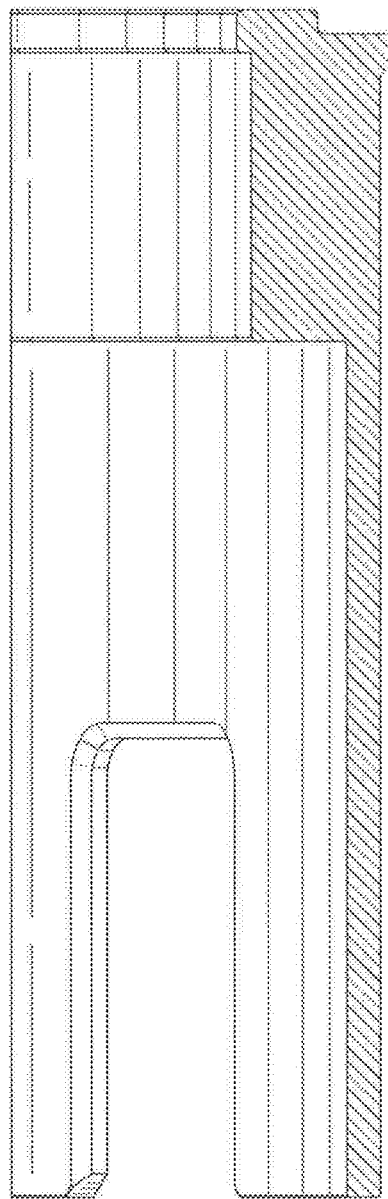


FIG. 9